



Material Content Data Sheet



Sales Product Name	BFP 183 E7764	Issued	10. May 2021
MA#	MA001617930		
Package	PG-SOT143-4-1	Weight*	11.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000			42	
	noble metal	gold	7440-57-5	0.002	0.02		163	
	inorganic material	silicon	7440-21-3	0.016	0.14	0.16	1408	1613
leadframe	non noble metal	nickel	7440-02-0	1.673	15.12		151217	
	non noble metal	iron	7439-89-6	2.310	20.88	36.00	208824	360041
wire	noble metal	gold	7440-57-5	0.016	0.15	0.15	1477	1477
encapsulation	organic material	carbon black	1333-86-4	0.104	0.94		9438	
	inorganic material	antimonytrioxide	1309-64-4	0.157	1.42		14157	
	plastics	brominated resin	-	0.196	1.77		17696	
	plastics	epoxy resin	-	1.631	14.75		147467	
	inorganic material	silicondioxide	60676-86-0	4.437	40.11	58.99	401108	589866
leadfinish	non noble metal	tin	7440-31-5	0.217	1.96	1.96	19582	19582
plating	noble metal	silver	7440-22-4	0.303	2.74	2.74	27421	27421
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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